DOCUMENT CHANGE REQUEST

DCR number 1057	Changes required for: General	Originator: Steve Thacker
Date: 2017/11/27	Date sent: 2017/01/30	Organisation: ESCC Executive Secretariat
Status: IMPLEMENTED		

Title:	Preservation Packaging and Despatch of SCC Components		
Number:	20600	Issue:	4

Other documents affected:

Page:

5, 6

Paragraph:

2 & 4.1

Original wording:

as per ESCC 20600 issue 3

Proposed wording:

See attached ESCC 20600 Draft 4B that highlights the proposed changes per this DCR in yellow.
i.e.

A) Amend Para. 2 to include a separate Reference Documents paragraph 2.2 as follows:

2 RELATED DOCUMENTS

2.1 APPLICABLE DOCUMENTS
The following documents form part of this specification and shall be read in conjunction with it:
(a) ESCC Basic Specification No. 21700, General Requirements for the Marking of ESCC Components.
(b) ESCC Basic Specification No. 23800, Electrostatic Discharge Sensitivity Test Method.

2.2 REFERENCE DOCUMENTS
IEC Technical Report 62258-3, Semiconductor die products – Part 3: Recommendations for good practice in handling, packing and storage

B) Add a new final sub-para to Para 4.1 as follows:
4.1 GENERAL

Specific requirements and recommendations for handling, packaging and storage of semiconductor die components are given in Para. 4.1.1.

DOCUMENT CHANGE REQUEST

DCR number 1057	Changes required for: General	Originator: Steve Thacker
Date: 2017/11/27	Date sent: 2017/01/30	Organisation: ESCC Executive Secretariat
Status: IMPLEMENTED		

C) Add new Para. 4.1.1 as follows:
4.1.1 Specific Requirements and Recommendations for Handling, Packaging and Storage of Semiconductor Die Components

Recommendations for good practice in handling, packaging and storage of semiconductor die components are given in IEC TR 62258-3.

Any specific requirements applicable to a particular semiconductor die component with respect to handling, packaging and storage shall be as specified in the applicable Detail Specification.

Justification:

This DCR is raised in line with PSWG action AI#77.7:
to raise a DCR for ESCC22600 to include requirements for the handling, packing, storage of bare dies, etc.

Attachments:

escc_20600_draft_4b_(proposed_dcr_handling_and_storage_of_die).docx,
escc_20600_draft_4f_(dcrs_1057_&_1084)_per_pswg80_decision.docx, null

Modifications:

N/A

Approval signature:



Date signed:

2017-11-27